

Title (en)

INTEGRATED CIRCUIT WITH SEVERAL COMPONENTS AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

INTEGRIERTE SCHALTUNGSANORDNUNG MIT MEHREREN BAUELEMENTEN UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

CIRCUIT INTEGRE A PLUSIEURS COMPOSANTS ET SON PROCEDE DE PRODUCTION

Publication

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Application

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Priority

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Abstract (en)

[origin: DE19716102A1] The invention relates to an integrated circuit containing several components, at least one of which is coated by a metallic shielding structure. This component is thus protected from interfering incoupled impulses from its surroundings. The circuit components can, in particular, be fitted next to or on top of each other. In order to produce the metallic shielding structure of a circuit component, at least one indent is produced, which surrounds the component, and which is then lined with metal. The contacts and electric connections of the component are electrically insulated by the metal of the shielding structure. In order to combine two components inside a three-dimensional circuit, the surfaces of the component that face each other can be coated with two different metals, the alloy of which has a melting temperature T_s above the melting temperature T_1 of at least one of the metals, as a result of which heating to a temperature between the two melting temperatures leads to a firm assembly.

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